

Electronic Patent Application Fee Transmittal

Application Number:	10719912			
Filing Date:	21-Nov-2003			
Title of Invention:	Method of fabricating a thermally enhanced wafer-level chip scale package			
First Named Inventor/Applicant Name:	Tzong Da Ho			
Filer:	Steven M. Jensen			
Attorney Docket Number:	55855-DIV (71987)			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 2 months with \$0 paid	1252	1	450	450

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				450